INTEGRATED CIRCUITS

DATA SHEET

74F30 8-input NAND gate

Product specification

1989 Mar 03

IC15 Data Handbook





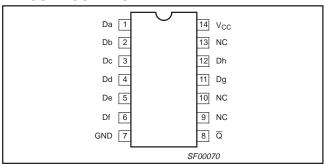
74F30

	TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
7	4F30	3.2ns	1.7mA

ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C	PKG DWG #
14-pin plastic DIP	N74F30N	SOT27-1
14-pin plastic SO	N74F30D	SOT108-1

PIN CONFIGURATION

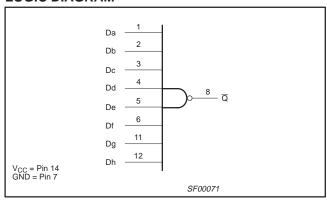


INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	PINS DESCRIPTION		LOAD VALUE HIGH/LOW		
Dn	Data inputs	1.0/1.0	20μA/0.6mA		
Q	Data output	50/33	1.0mA/20mA		

NOTE: One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

LOGIC DIAGRAM



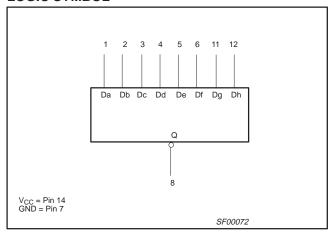
FUNCTION TABLE

	INPUTS											
Dna	Dnb	Dnc	Dnd	Dne	Dnf	Dng	Dnh	Qn				
L	Х	Χ	Х	Χ	Х	Х	Х	Н				
X	L	Χ	Χ	Χ	Χ	Χ	Χ	Н				
Х	Χ	L	Χ	Χ	X	Χ	Χ	Н				
Х	Χ	Χ	L	Χ	Χ	Χ	Χ	Н				
Х	Χ	Χ	Χ	L	Χ	Χ	Х	Н				
X	Χ	Χ	Χ	Χ	L	Χ	Χ	Н				
X	Χ	Χ	Χ	Χ	X	L	Χ	Н				
Х	Χ	Χ	Χ	Χ	Χ	Χ	L	Н				
Н	Н	Н	Н	Н	Н	Н	Н	Ĺ				

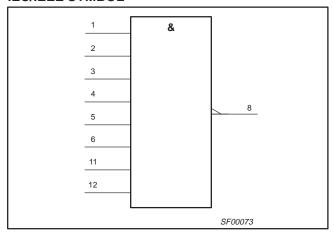
NOTES:

- 1. H = High voltage level
- 2. L = Low voltage level
- 3. X = Don't care

LOGIC SYMBOL



IEC/IEEE SYMBOL



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8-input NAND gate

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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	−30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state	40	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	DADAMETED		UNIT			
STMBOL	PARAMETER	MIN	NOM	MAX	ONII	
V _{CC}	Supply voltage	4.5	5.0	5.5	V	
V _{IH}	High-level input voltage	2.0			V	
V _{IL}	Low-level input voltage			0.8	V	
I _{IK}	Input clamp current			-18	mA	
I _{OH}	High-level output current			-1	mA	
I _{OL}	Low-level output current			20	mA	
T _{amb}	Operating free-air temperature range	0		+70	°C	

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

CVMDOL	DADAMETED	TEST COMPLTIC	TEST CONDITIONS ¹			LIMITS			
SYMBOL	PARAMETER	TEST CONDITIO				MAX	UNIT		
V	High level output valtage	V _{CC} = MIN, V _{IL} = MAX	±10%V _{CC}	2.5			.,		
V _{OH}	High-level output voltage	$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V		
V	Low lovel output voltoge	$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}		0.30	0.50	V		
V _{OL}	Low-level output voltage	$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.30	0.50	v		
V _{IK}	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V			
I _I	Input current at maximum input voltage	$V_{CC} = MAX, V_I = 7.0V$			100	μΑ			
I _{IH}	High-level input current	$V_{CC} = MAX, V_I = 2.7V$				20	μΑ		
I _{IL}	Low-level input current	$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA		
Ios	Short-circuit output current ³	V _{CC} = MAX		-60		-150	mA		
1	Supply current (total)	VMAY	V _{IN} = GND	V _{IN} = GND 0.6		1.5	m ^		
Icc	I _{CCL}	V _{CC} = MAX	V _{IN} = 4.5V		2.8	4.0	mA		

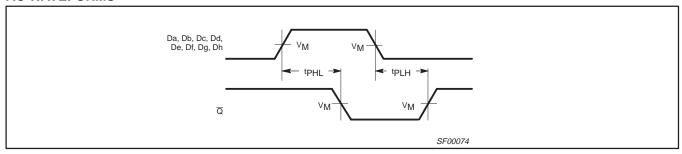
NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
- 3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	Ta	/ _{CC} = +5.0 _{amb} = +25° 50pF, R _L =	C	V _{CC} = +5. T _{amb} = 0°0 C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay Da, Db, Dc, Dd, De, Df, Dg, Dh to $\overline{\mathbb{Q}}$	Waveform 1	1.5 1.0	3.5 3.0	5.0 4.5	1.5 1.0	5.5 5.0	ns

AC WAVEFORMS



Waveform 1. Propagation Delay for Inverting Outputs

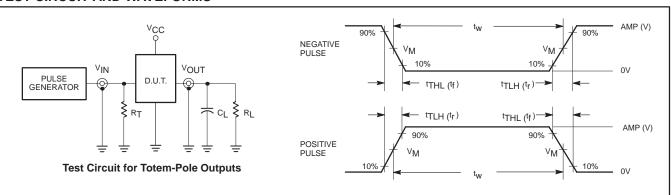
NOTE:

For all waveforms, $V_M = 1.5V$.

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TEST CIRCUIT AND WAVEFORMS



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DEFINITIONS:

R_L = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.

 $C_L = Load$ capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

Termination resistance should be equal to Z_{OUT} of pulse generators.

Input	Pulse	Definition
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family	INP	INPUT PULSE REQUIREMENTS									
	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}					
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns					

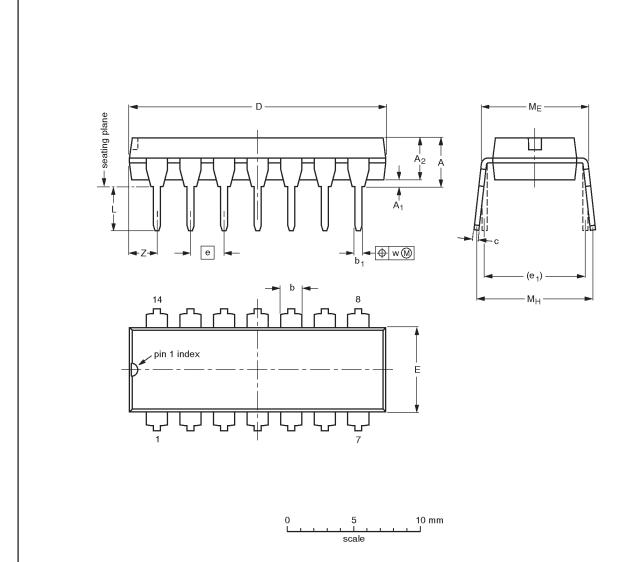
SF00006

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11	

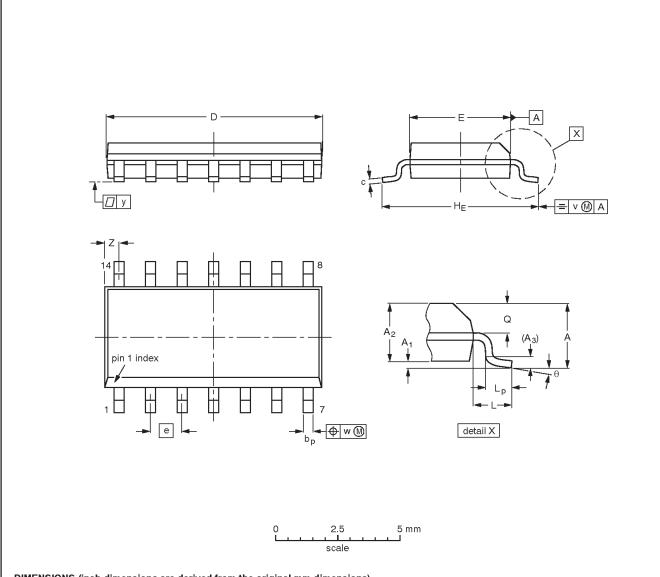
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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	У	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE	
SOT108-1	076E06S	MS-012AB				-95-01-23- 97-05-22	

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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